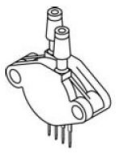
MPX2202xP, MPXV2202DP
MPXV2202GC6, MPXM2202xS

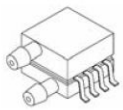
Datasheet

0 to 200 kPa (0 to 29 psi) 40 mV full scale (typical)

MPX2202GP
CASE 344B-01



MPX2202DP
CASE 344C-01



MPXV2202DP
CASE 1351-01

MPXV2202GC6T1
CASE 482A-01

MPXM2202GS/AS
CASE 1320A-02

Features

- Temperature Compensated Over 0°C to +85°C
- Easy-to-Use Chip Carrier Package Options
- Available in Absolute, Differential and Gauge Configurations
- Ratiometric to Supply Voltage
- Available in Easy-to-Use Tape and Reel

Applications

- Pump/Motor Controllers
- Robotics
- Level Indicators
- Medical Diagnostics
- Pressure Switching
- Barometers
- Altimeters

Description

The MPX2202 devices series are silicon piezoresistive pressure sensor providing a highly accurate and linear voltage output directly proportional to the applied pressure. The sensor is a single monolithic silicon diaphragm with the strain gauge and a thin-film resistor network integrated on chip. The chip is laser trimmed for precise span and offset calibration and temperature compensation. They are designed for use in applications such as pump/motor controllers, robotics, level indicators, medical diagnostics, pressure switching, barometers, altimeters, etc.

1 Ordering information

ORDERING INFORMATION								
Device Name	Case No.		# of Ports		Pressure Type			Device Marking
		None	Single	Dual	Gauge	Differential	Absolute	
Unibody Package (MPX2202 Series)								
MPX2202DP	344C			•		•		MPX2202DP
MPX2202GP	344B		•		•			MPX2202GP
Small Outline Package (MPXV2202 Series)								
MPXV2202DP	1351			•		•		MPXV2202DP
MPXV2202GC6T1	482A		•		•			MPXV2202G
MPAK Package (MPXM2202 Series)								
MPXM2202GS	1320A		•		•			MPXM2202GS
MPXM2202GST1	1320A		•		•			MPXM2202GS
MPXM2202AS	1320A		•				•	MPXM2202AS

2 Operating Characteristics

Table 1. Operating Characteristics
(V_S = 10 Vdc, T_A = 25°C unless otherwise noted, P1 > P2)

Characteristics	Symbol	Min	Typ	Max	Unit
Pressure Range(1) Absolute Pressure Range MPX2202A Differential Pressure Range MPX2202D	 P_{OP} P_{OP}	 20 0	 — —	 200 200	 kPa kPa
Supply Voltage(2)	V_S	—	10	16	Vdc
Supply Current	I_o	—	6.0	—	mAdc
Full Scale Span(3)	V_{FSS}	38.5	40	41.5	mV
Offset(4) MPX2202D, MPXM2202D/G Series MPX2202A, MPXM2202A Series	V_{off}	 -1.0 -2.0	 — —	 1.0 2.0	mV
Sensitivity	ΔV/ΔP	—	0.2	—	mV/kPa
Linearity(5) MPXM2202D/G, MPX2202D Series MPXM2202A, MPX2202A Series	—	 -0.6 -1.0	 — —	 0.4 1.0	$\%V_{FSS}$
Pressure Hysteresis(5) (0 to 200 kPa)	—	—	±0.1	—	$\%V_{FSS}$
Temperature Hysteresis(5) (-40 °C to +125 °C)	—	—	±0.5	—	$\%V_{FSS}$
Temperature Effect on Full Scale Span(5)	TCV_{FSS}	-2.0	—	2.0	$\%V_{FSS}$
Temperature Effect on Offset(5)	TCV_{off}	-1.0	—	1.0	mV
Input Impedance	Z_{in}	1000	—	2500	Ω
Output Impedance	Z_{out}	1400	—	3000	Ω
Response Time(6) (10% to 90%)	t_R	—	1.0	—	ms
Warm-Up	—	—	20	—	ms
Offset Stability(7)	—	—	±0.5	—	$\%V_{FSS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.
3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
4. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
5. Accuracy (error budget) consists of the following:

   Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.

   Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

   Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.

   TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85°C, relative to 25°C.

   TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.

6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

3 Maximum Ratings

Table 2. Maximum Ratings(1)

Rating	Max Value	Unit
Maximum Pressure (P1 > P2)	400	kPa
Storage Temperature	-40 to 125	°C
Operating Temperature	-40 to 125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

4 Voltage Output versus Applied Differential

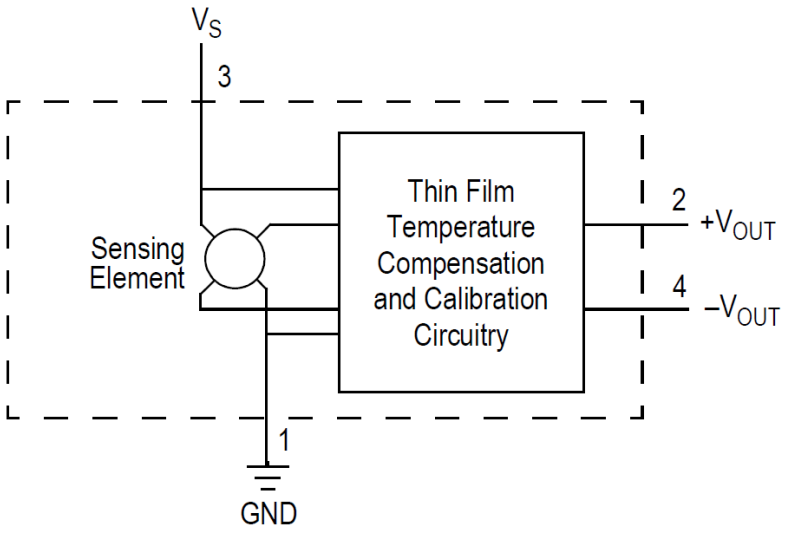
The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The absolute sensor has a built-in reference vacuum. The output voltage will decrease as vacuum, relative to ambient, is drawn on the pressure (P1) side.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure (P1) side relative to the vacuum (P2) side. Similarly, output voltage increases as increasing vacuum is applied to the vacuum (P2) side relative to the pressure (P1) side.

Figure 1 illustrates a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

Figure 1. Temperature Compensated and Calibrated Pressure Sensor Schematic



5 On-Chip Temperature Compensation and Calibration

Figure 2. Output vs. Pressure Differential

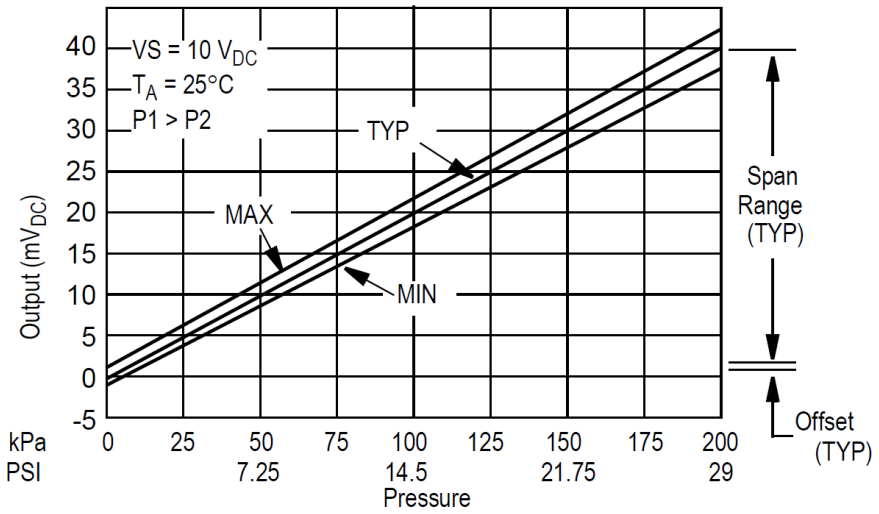


Figure 2 shows the output characteristics of the MPX2202 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

The effects of temperature on full scale span and offset are very small and are shown under Operating Characteristics.

Figure 3. Cross Sectional Diagram (not to scale)

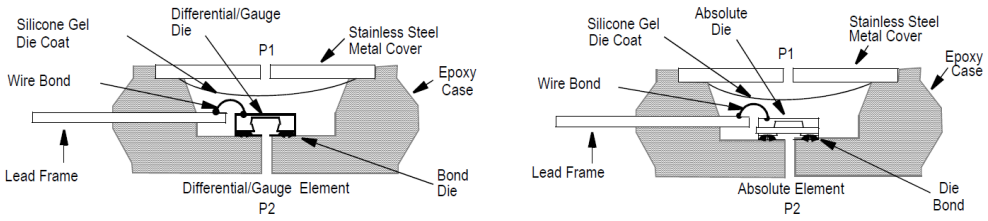


Figure 3 illustrates the differential/gauge die in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

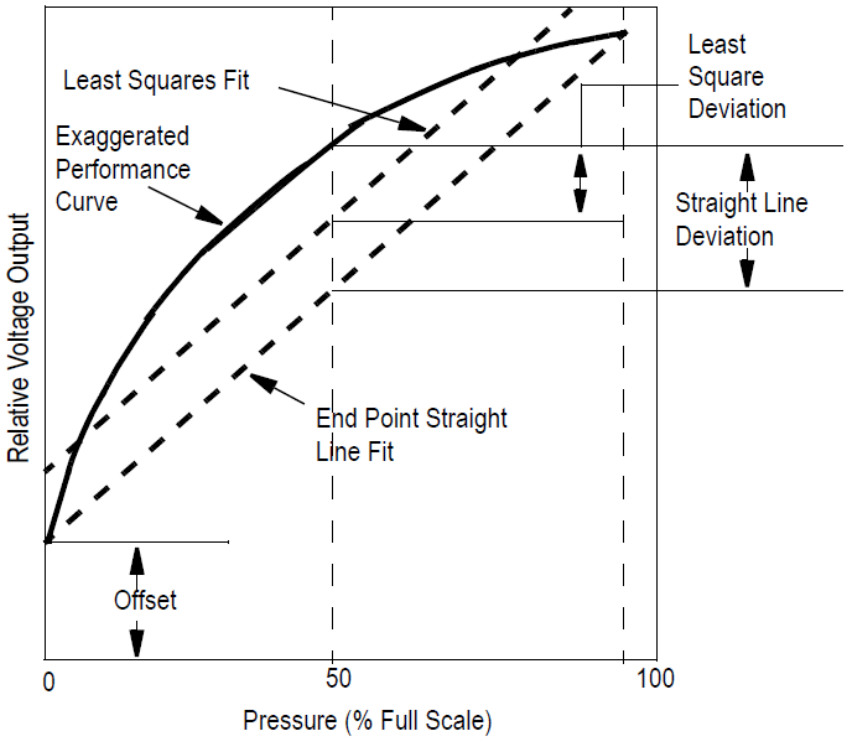
The MPX2202 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.

6 LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off}$ + sensitivity x P over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 4) or (2) a least squares best line fit. While a least squares fit gives the “best case” linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the “worst case” error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. ST’s specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

Figure 4. Linearity Specification Comparison



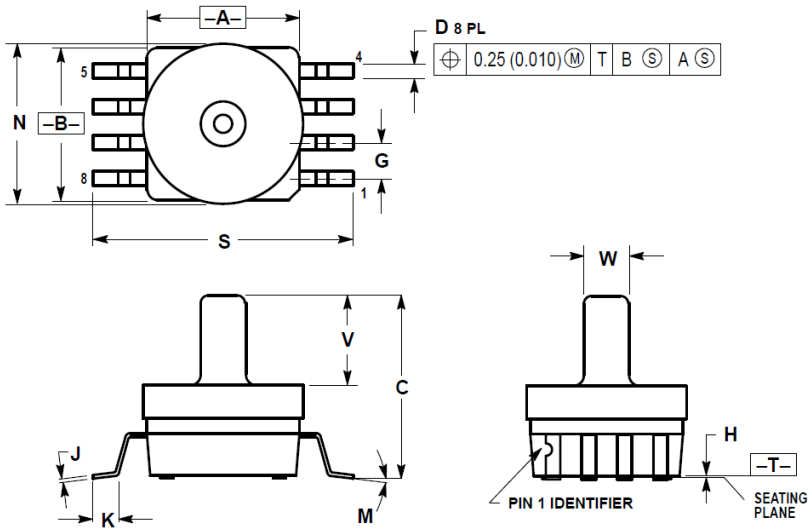
7 PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

ST designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing silicone gel which isolates the die from the environment. The ST MPX pressure sensor is designed to operate with positive differential pressure applied, P1 > P2. The Pressure (P1) side may be identified by using the following table.

Table 1. Pressure (P1) Side Delineation

Part Number	Case Type	Pressure (P1) Side Identifier
MPX2202DP	344C	Side with Part Marking
MPX2202GP	344B	Side with Port Attached
MPXV2202DP	1351	Side with Part Marking
MPXV2202GC6T1	482A	Side with Port Attached
MPXM2202GS/AS	1320A	Side with Port Attached

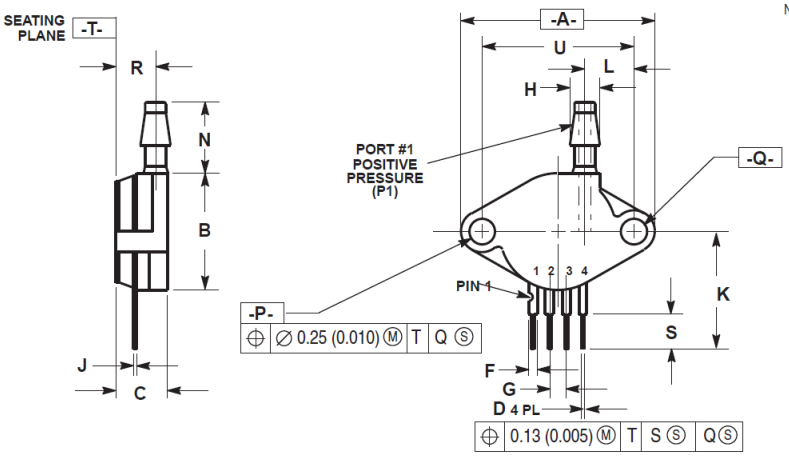
8 PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.500	0.520	12.70	13.21
D	0.038	0.042	0.96	1.07
G	0.100 BSC		2.54 BSC	
H	0.002	0.010	0.05	0.25
J	0.009	0.011	0.23	0.28
K	0.061	0.071	1.55	1.80
M	0°	7°	0°	7°
N	0.444	0.448	11.28	11.38
S	0.709	0.725	18.01	18.41
V	0.245	0.255	6.22	6.48
W	0.115	0.125	2.92	3.17

CASE 482A–01
ISSUE A

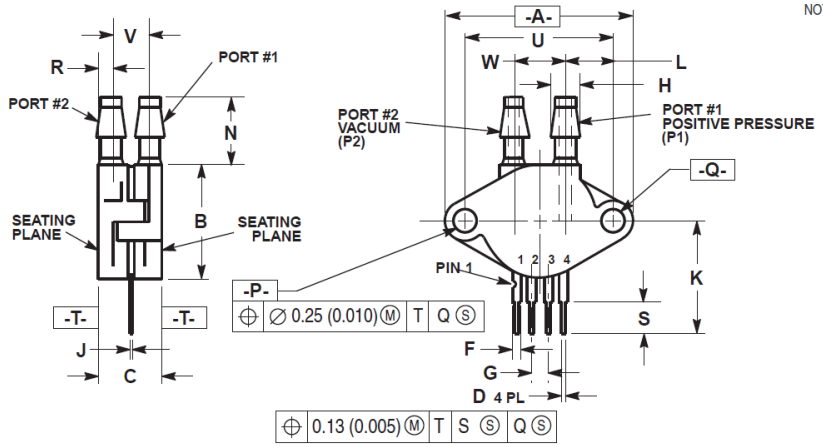


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	

STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. - OUTPUT

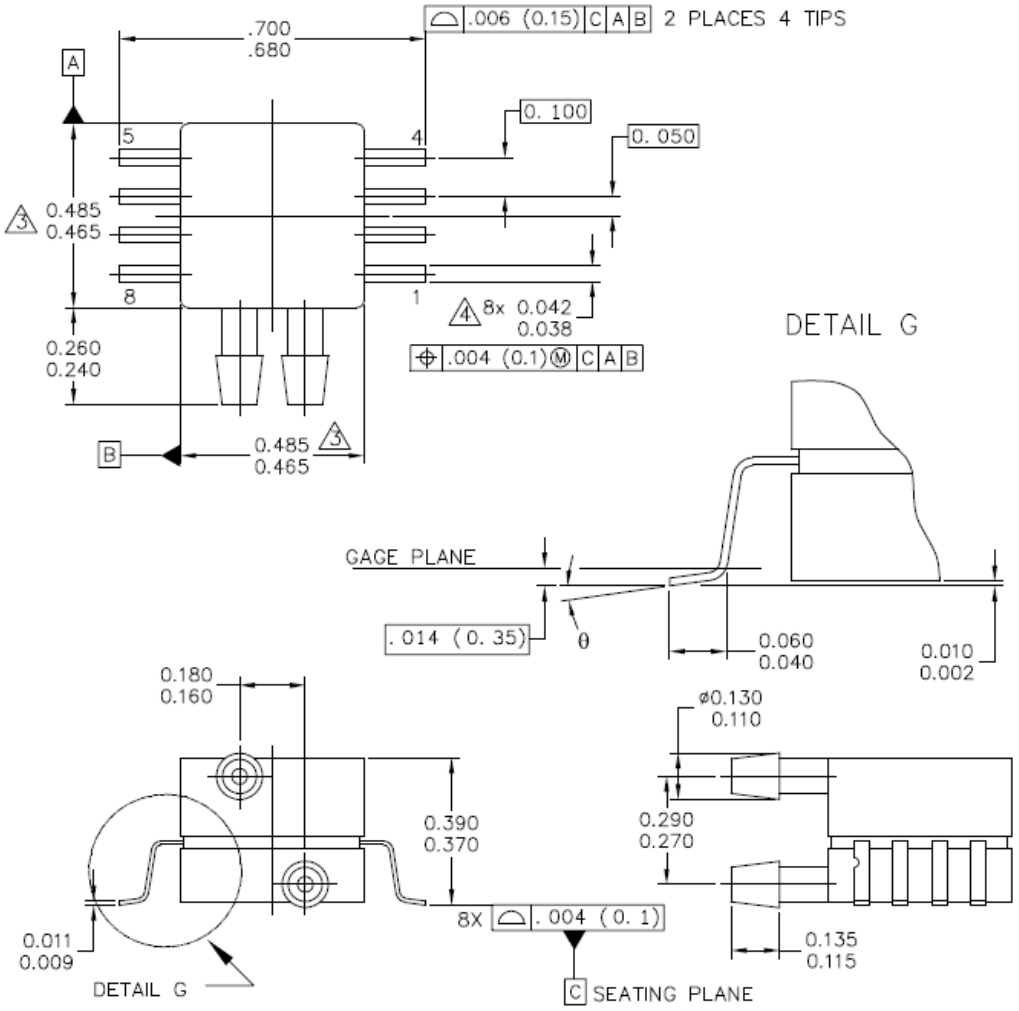
CASE 344B-01
ISSUE B
UNIBODY PACKAGE



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.248	0.278	6.30	7.06
W	0.310	0.330	7.87	8.38

CASE 344C-01
ISSUE B
UNIBODY PACKAGE



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	CASE NUMBER: 1351-01	27 JUL 2005
	STANDARD: NON-JEDEC	

CASE 1351-01
ISSUE A
SMALL OUTLINE PACKAGE

PAGE 1 OF 2

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PPROTRUSIONS. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

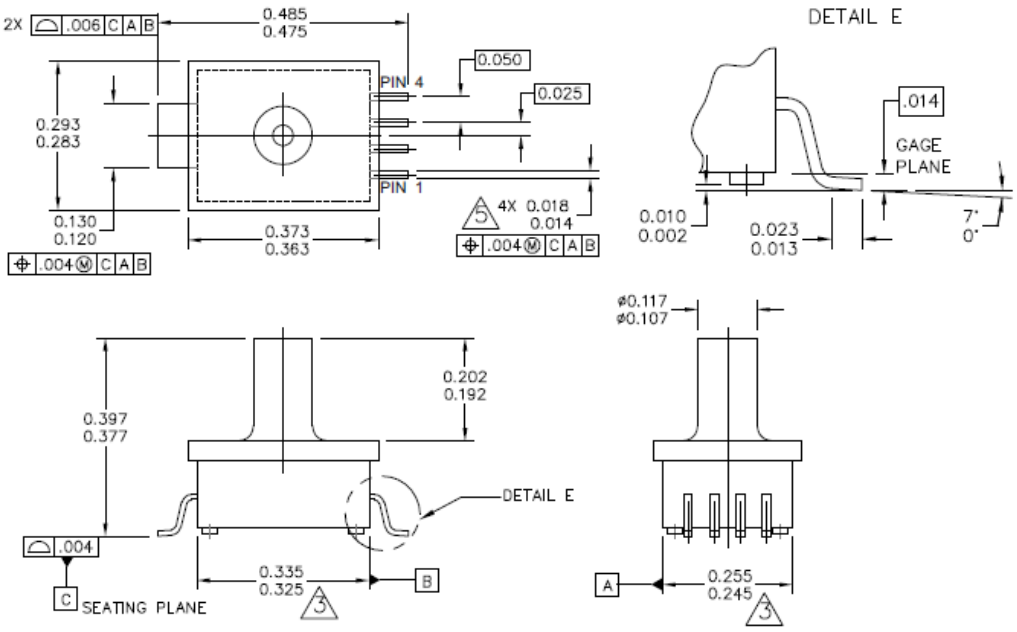
STYLE 1:	STYLE 2:
PIN 1: GND	PIN 1: N/C
PIN 2: +Vout	PIN 2: Vs
PIN 3: Vs	PIN 3: GND
PIN 4: –Vout	PIN 4: Vout
PIN 5: N/C	PIN 5: N/C
PIN 6: N/C	PIN 6: N/C
PIN 7: N/C	PIN 7: N/C
PIN 8: N/C	PIN 8: N/C

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ASA99255D	REV: A
8 LD SNSR, DUAL PORT	CASE NUMBER: 1351–01	27 JUL 2005
	STANDARD: NON–JEDEC	

PAGE 2 OF 2

CASE 1351-01
ISSUE A
SMALL OUTLINE PACKAGE



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	CASE NUMBER: 1320A–02	22 JUL 2005
	STANDARD: NON–JEDEC	

CASE 1320A-02
ISSUE A
MPAK

NOTES:

1. DIMENSIONS ARE IN INCHES.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5" MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ARH99087A	REV: A
5 LD M–PAC, PORTED	CASE NUMBER: 1320A–02	22 JUL 2005
	STANDARD: NON–JEDEC	

CASE 1320A-02
ISSUE A
MPAK

Revision history

Table 2. **Document revision history**

Date	Version	Changes
07-Jul-2026	1	Initial release from ST, rebranded NXP document